

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows:

On Page 1 of the specification, please insert the following Related Applications section:

-- RELATED APPLICATIONS

1
B The present application is a U.S. National Phase Application under 35 U.S.C. § 371 of PCT Application No. PCT/US99/06453 filed March 26, 1999, and claims the benefit of U.S. Provisional Application Serial No. 60/079,746 filed March 27, 1998, the entire disclosures of which are both expressly incorporated herein by reference. --

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On Page 6 of the specification, please amend the paragraph beginning on line 25 as follows:

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B -- The display shown in FIG. 1 is manufactured in a sequence of steps that adds the TFT and OLED layers to one substrate. A substrate foil, for example, stainless steel, has patterned TFT circuits added first. The OLED circuits are then placed on the substrate. Optionally, a plastic substrate could be provided, and active electronics can be formed thereon. A transparent encapsulation layer (not shown) is then applied. The top contact to the OLED layer must be transparent to transmit the light, which is emitted from the organic semiconductor. In this structure this contact is made in one of the last processing steps. It was found experimentally that this transparent contact to the OLED functions best when made first, i.e., when the OLED is made on top of it ("*Organic LEDs integrated with a-Si TFTs on lightweight metal substrates*",

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C.C. Wu, et al., Society of Information Display, Internat. Symp. Digest, Vol. XXVIII, SID, Santa Ana, CA 1997, pp. 67-70). However, making the OLEDs first on a transparent substrate, followed by making the TFTs on top of the OLEDs is not possible, because the typical TFT process temperature of 200° to 350° C will destroy the OLED, which must not be heated much above room temperature. --
